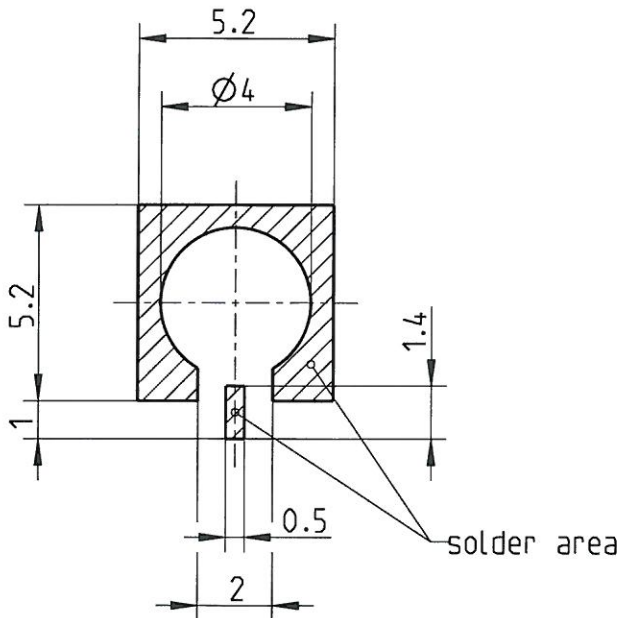


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Leiterplatten-Layout
PCB layout
B 120



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.

Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.

In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

Formzahl: TCC_F8_05_P8_A4_Einzelteil
Datei: AL_LINTECH_EDM_FPM
Version: 1.0

-METRIC-



ISO-Projektion
Methode E

Rosenberger Hochfrequenztechnik 84526 Tittmoning Pro/ENGINEER		general tolerance ISO 2768 RN 006-01 m-H dimensions <0,5 and symmetry		scale: 5:1	weight(g): surface(mm²):
				material:	
		date name drawn 14.11.2005 A_Nobis check 30.11.05 <i>LL</i> appr. 2/12/05 <i>pat</i>		title: Leiterplatten-Layout PCB layout	
		dimensioning incl. finish		part-no...: MB_120	
a00	05-0615	A_Nobis	15.11.2005	sheet: 1	
rev.	change-no	name	date	distribu- tion to:	of: 1
				FE AZ QSM RMT .	remarks: .
				X	